

<b>Job ID:</b>	250RK
Job Title:	Director of Engineering
Degree Requirements:	B.S. Electrical Engineering, Materials Science, Solid State Physics, relevant engineering, or physical science discipline
Years of Experience:	15+
Type of Position:	Direct Hire / Full Time
Location:	North of New York City
Salary Range:	D.O.E.
Travel Required:	20% ( Domestic & International )

Our New York based client has an **IMMEDIATE NEED** for a **Director of Engineering** who has 15+ years experience and expertise. The company offers a very attractive benefits package including relocation assistance. The position is Bonus Eligible.

**Candidates who require a Visa WILL NOT BE CONSIDERED.**

The **MUST HAVE REQUIREMENTS** for this position are:

- \* Bachelors Degree in one of the following: Electrical Engineering, Engineering, Solid State Physics, relevant engineering, or physical science discipline
- \* 10 or more years of leadership / management experience leading a large multi-shift, multi-cultural team in the semi-conductor industry
- \* Outstanding communication & interaction skills
- \* Ability to influence & lead initiatives cross-functionally, both internally & externally that have global reach
- \* Strong organizational skills
- \* Verifiable ability to manage multiple tasks simultaneously
- \* Ability to react to shifting priorities to meet business needs, deadlines & commitments
- \* Strong interpersonal skills
- \* Ability to work effectively with different cultures & levels of organization
- \* Proven effective organizational & leadership skills, with the ability to work well with all levels of the organization

**PLUSSES** in this position are:

- \* MS or PhD in one of the above disciplines is **STRONGLY PREFERRED**
- \* Experience in a foundry environment managing multiple technology nodes & products
- \* Experience in leading edge technology nodes ( sub-65nm node ) including derivative technologies such as RF, analog / mixed signal, non-volatile memory, low power, high voltage
- \* Six Sigma / Lean expertise

Reporting to the Executive Team, the **RESPONSIBILITIES** include but are not limited to:

- \* Leadership & positive execution in semiconductor technology development
- \* Staffing & development of the Front End of Line ( FEOL ) & Back End of Line ( BEOL ) Integration team
- \* Work closely with the Director of Technology Integration to create & execute a staffing & training plan for the FEOL Integration team ( engineers, technicians, & support staff ) supporting the Fab2 technology & production goals ( start-up to production ramp to sustaining development work)
- \* Manage all human resources processes ( training, developing & coaching managers, recruiting & hiring, performance management, compensation planning, training & development of staff, succession planning & retention )
- \* Insure successful set up by the FEOL integration team of process flows for technologies transferring into Fab2 & insure matching of the resulting integrated process to electrical, physical, reliability, yield / defectivity & cost requirements
- \* Debug and resolve all FEOL issues of manufacturing technologies during installation, production ramp and high volume manufacturing working closely with process modules, yield engineering, and customer / product engineering
- \* Define & execute with counterparts in Fab1 ( European ) and/or R&D technology transfer plans for bringing

technologies into Fab2 including cross-site technology transfer activities ( ex-pat assignments, wafer exchanges, technology transfer meetings, etc )

- \* Interact with program management offices creating project plans, deliverables, resource plans
- \* Effectively manage the execution of multiple concurrent technology nodes running in Fab2
- \* Engage with the R&D organization on providing manufacturing inputs into the definition & development of new technology nodes with manufacturability, cost and yield expectations
- \* Provide continuous engagement in R&D program reviews guiding & supporting R&D activities before technology Transfer
- \* Support the process modules ( etch, thin films, diffusion, litho, CMP )
- \* Support facilities teams on process chemical & equipment requirements for start-up / introduction of new technology nodes to manufacturing
- \* Work with Industrial Engineering, Lean Manufacturing, Yield and Product Engineering identifying & resolving production needs of new technologies & continuously improve manufacturing effectiveness driving cost reductions

If you meet these requirements and wish to be considered for this position, send your résumé to us in a Word document at [Resumes@PinnaclePlacementGroup.com](mailto:Resumes@PinnaclePlacementGroup.com) mentioning the **Job ID** and the **Job Title** in the subject line of your email.

**In your email or cover letter, please provide us a short narrative detailing your experience and expertise as it applies to this position. Also, please provide us with your *MINIMUM* salary requirements.**

**KEY WORDS:** New York, NY, manufacturing, BS Electrical Engineering, BS Materials Science Engineering, BS Solid State Physics, BS Chemical Engineering, BSEE, BS ChmE, BS Chemistry, BS Physics, BS Optics, BS Microscopy, Semi Conductors, Semiconductors, Lean Manufacturing, Six Sigma, Lean Six Sigma, defect reduction, inspection, process improvement, MS Electrical Engineering, MS Materials Science Engineering, MS Solid State Physics, MS Chemical Engineering, MSEE, MS ChmE, MS Chemistry, MS Physics, MS Optics, MS Microscopy, PhD Electrical Engineering, PhD Materials Science Engineering, PhD Solid State Physics, PhD Chemical Engineering, sub-65nm node, derivative technologies, RF, analog / mixed signal, non-volatile memory, low power, high voltage, Front End of Line, FEOL, Back End of Line, BEOL Integration, Fab2